What is claimed is:

1	1. A method of encapsulating a display element, comprising
2	steps of:
3	providing an organic light emitting diode or a plastic light
4	emitting diode, comprising a luminescent body formed on a glass
5	substrate and a glass cap with a rib structure formed on the
6	bottom surface thereof;
7	coating a sealing layer of frit on the rim of the glass cap
8	and surrounding the rib structure;
9	providing a pedestal on which the display element is placed;
10	providing a pressing plate disposed on the display element;
11	providing a high-power beam penetrating the glass cap to
12	focus on the sealing layer so as to sinter the frit; and
13	applying pressure on the pedestal and the pressing plate.
14	
1	2. The method of encapsulating a display element according
2	to claim 1, wherein the pedestal and the pressing plate are of
3	metal materials with good thermal conductivity.
4	
1	3. The method of encapsulating a display element according
2	to claim 1, wherein the high-power beam is a laser beam.
3	

4. The method of encapsulating a display element according 1 2 to claim 1, wherein the laser beam has a wavelength exceeding 550nm. 3 4 5. The method of encapsulating a display element according 1 2 to claim 1, wherein the high-power beam is an infrared ray. 3 6. The method of encapsulating a display element according 1 to claim 1, wherein the infrared ray has a wavelength exceeding 2 3 800nm. 4 7. The method of encapsulating a display element according 1 to claim 1, wherein the rib structure is frit. 2 3 8. The method of encapsulating a display element according 1 2 to claim 1, wherein the rib structure is of ceramic materials. 3 1 9. The method of encapsulating a display element according to claim 1, wherein the luminescent body is laminated with at 2 3 least an anode layer, an organic luminescent layer and a cathode 4 layer. 5